



**GP**  
**ELECTRONICS**

**GPMN2012**

**20V N-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	$I_D$
20V	10m $\Omega$ @4.5V	12A
	14m $\Omega$ @2.5V	
	23m $\Omega$ @1.8V	

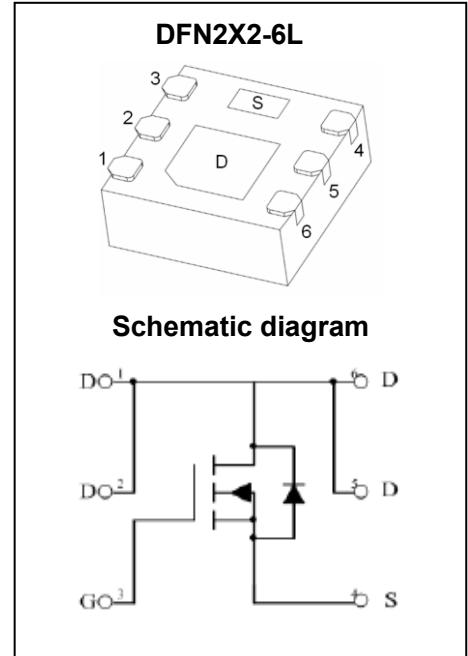
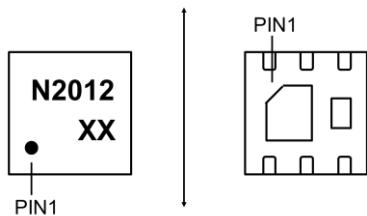
### FEATURES

- TrenchFET Power MOSFET
- Small package DFN2X2-6L

### APPLICATION

- Load Switch for Portable Applications

### MARKING:



### ABSOLUTE MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Continuous Drain Current <sup>1,2</sup>	$I_D$	12	A
Plused Drain Current	$I_{DM}$	40	A
Power Dissipation	$P_D$	0.75	W
Thermal Resistance from Junction to Ambient <sup>1,2</sup>	$R_{\theta JA}$	167	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	55~+150	°C

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>A</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drainsource breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V			1	μA
Gatebody leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±10V, V <sub>DS</sub> = 0V			±100	nA
<b>On Characteristics</b>						
Gate threshold voltage <sup>3</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.7	1.0	V
Drainsource onresistance <sup>3</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A		10	15	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A		14	18	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 3A		23	30	
Forward tranconductance <sup>3</sup>	g <sub>F</sub>	V <sub>DS</sub> = 4V, I <sub>D</sub> = 10A	10			S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		648		pF
Output Capacitance	C <sub>oss</sub>			156		
Reverse Transfer Capacitance	C <sub>rss</sub>			7		
<b>Switching Characteristics</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 4V, V <sub>GS</sub> = 5V, I <sub>D</sub> = 10A		20		nC
GateSource Charge	Q <sub>gs</sub>			2.5		
GateDrain Charge	Q <sub>gd</sub>			6.5		
Turnon delay time	t <sub>d(on)</sub>	V <sub>GEN</sub> = 4.5V, V <sub>DD</sub> = 4V, R <sub>g</sub> = 1Ω, R <sub>L</sub> = 0.4Ω		15		ns
Turnon rise time	t <sub>r</sub>			10		
Turnoff delay time	t <sub>d(off)</sub>			70		
Turnoff fall time	t <sub>f</sub>			15		
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Current	I <sub>s</sub>				12	A
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 1A			1.2	V

Notes :

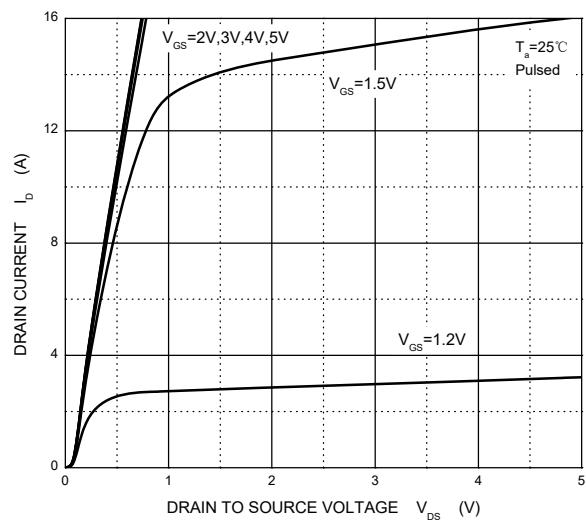
1.R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR4 board with 1oz. single side copper, in a still air environment with T<sub>A</sub> = 25°C.

2.R<sub>θJA</sub> is measured in the steady state

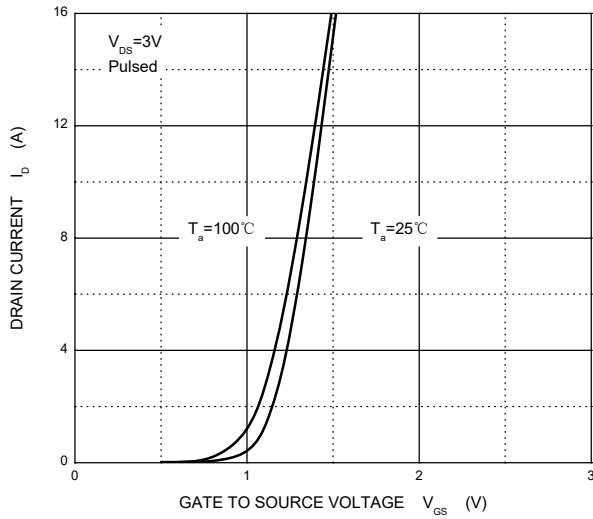
3.Pulse test : Pulse width ≤ 380μs, duty cycle ≤ 2%.

## Typical Electrical and Thermal Characteristics

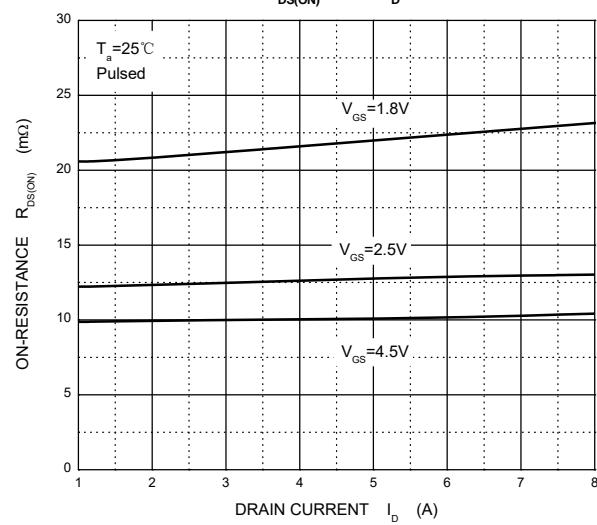
**Output Characteristics**



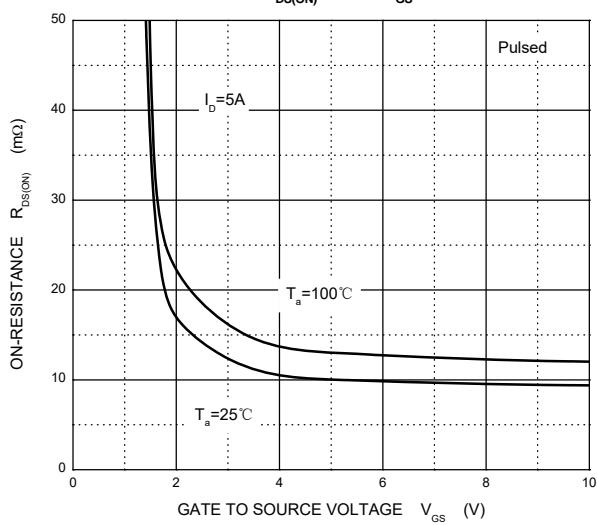
**Transfer Characteristics**



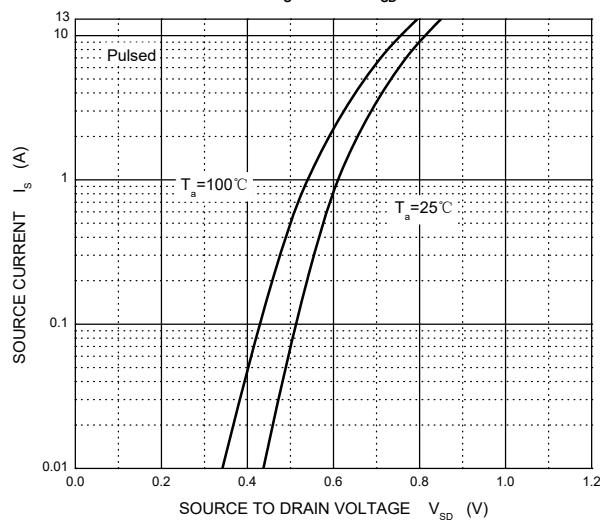
$R_{DS(ON)}$  —  $I_D$



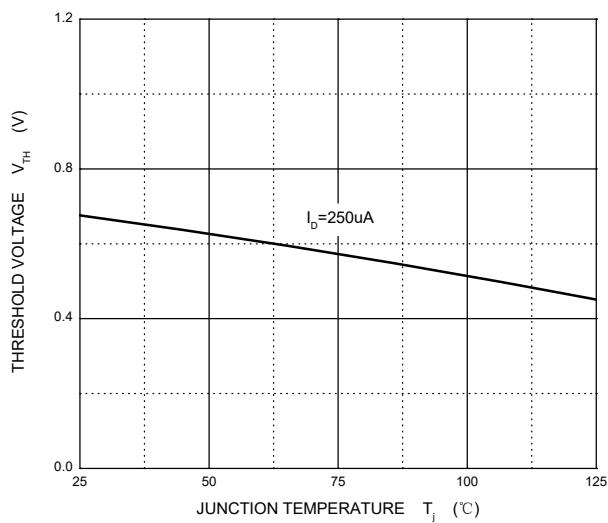
$R_{DS(ON)}$  —  $V_{GS}$

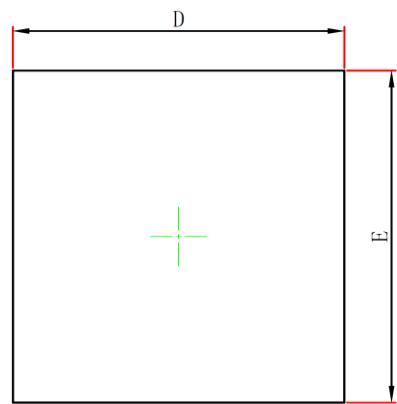


$I_s$  —  $V_{SD}$

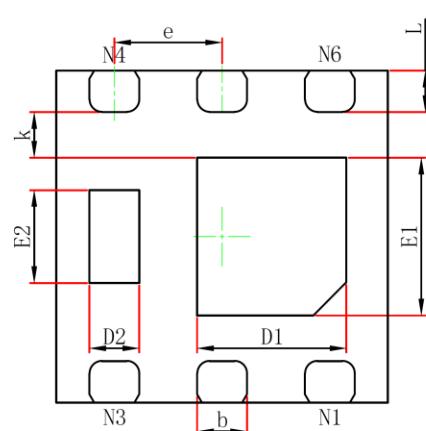


**Threshold Voltage**

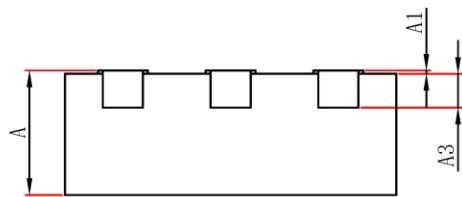


**DFN2X2-6L Package Information**


TOP VIEW



BOTTOM VIEW



SIDE VIEW

<b>Symbol</b>	<b>Dimensions In Millimeters</b>		<b>Dimensions In Inches</b>	
	<b>Min.</b>	<b>Max.</b>	<b>Min.</b>	<b>Max.</b>
A	0.700	0.800	0.028	0.031
A1	0	0.050	0	0.002
A3	2.03REF		0.008REF	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.65BSC		0.026TYP	
L	0.174	0.326	0.007	0.013